

<b>Notice of References Cited</b>	Application/Control No. 09/818,324	Applicant(s)/Patent Under Reexamination IWAMOTO ET AL.	
	Examiner Melvin Curtis Mayes	Art Unit 1734	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,667,884	09-1997	Bolger, Justin C.	428/323
	B	US-5,924,622	07-1999	Davis et al.	228/56.3
	C	US-6,580,035	06-2003	Chung, Kevin Kwong-Tai	174/255
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	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

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	N					
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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Brian Bauer and Rick Lathrop, "An Introduction to Solder Materials," Technical Papers, Heraeus Incorporated, 1999.
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.